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INTERNATIONAL STANDARD

NORME INTERNATIONALE

colour inside

Industrial communication networks – Profiles – Part 1: Fieldbus profiles

Réseaux de communication industriels – Profils – Partie 1: Profils de bus de terrain



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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INDUSTRIAL COMMUNICATION NETWORKS – PROFILES –

Part 1: Fieldbus profiles

FOREWORD

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NOTE Combinations of protocol types are specified in IEC 61784-1 and IEC 61784-2.

International Standard IEC 61784-1 has been prepared by subcommittee 65C: Industrial networks, of IEC technical committee 65: Industrial-process measurement, control and automation.

This fifth edition cancels and replaces the fourth edition published in 2014. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- update of the dated references to the IEC 61158 series, to IEC 61784-2, to the IEC 61784-3 series, to the IEC 61784-5 series and to IEC 61918 throughout the document;
- update of selection tables CPF 2, CPF 4 and CPF 8.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
65C/942/FDIS	65C/951/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This bilingual edition (2020-04) corresponds to the monolingual English version, published in 2019-05.

The French version of this standard has not been voted upon.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 61784 series, published under the general title *Industrial communication networks – Profiles*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

This document provides a set of Communication Profiles (CP) in the sense of ISO/IEC TR 10000-1. These answer the need of identifying the protocol families co-existing within the IEC 61158 series, as a result of the international harmonization of fieldbus technologies available on the market. More specifically, these profiles help to correctly state the compliance to the IEC 61158 series, and to avoid the spreading of divergent implementations, which would limit its use, clearness and understanding. Additional profiles to address specific market concerns, such as functional safety or information security, may be addressed by future parts of this standard.

This standard contains several Communication Profile Families (CPF), which specify one or more communication profiles. Such profiles identify, in a strict sense, protocol subsets of the IEC 61158 series via protocol specific communication profiles. They do not define device-type-specific communication profiles for the purpose of guiding manufacturers in feature set selection – for example, in selecting the minimum set of communication services and protocol to implement a specific class of devices, such as generic slaves or transmitters ("implementation profiles"). Neither do they define device profiles that specify communication profiles together with application functions needed to answer the need of a specific application ("application profiles").

It is agreed that these latter classes of profiles would help the use of the IEC 61158 series of standards; the profiles defined in this document are a necessary step to achieve that task.

It is also important to clarify that interoperability – defined as the ability of two or more network systems to exchange information and to make mutual use of the information that has been exchanged (see ISO/IEC TR 10000-1) – can be directly achieved on the same link only for those devices complying to the same communication profile.

Profiles contained in this International Standard are constructed of references to IEC 61158-2 and the IEC 61158-3, IEC 61158-4, IEC 61158-5 and IEC 61158-6 series, and other IS, TS or worldwide-accepted standards, as appropriate[1]. Each profile is required to reference at least one (sub)part of IEC 61158-2 through IEC 61158-6.

Two or more Profiles, which are related to a common family, are specified within a "Communication Profile Family" (CPF).

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[1] International Standardised Profiles may contain normative references to specifications other than International Standards; see ISO/IEC JTC 1 N 4047: *The Normative Referencing of Specifications other than International Standards in JTC 1 International Standardized Profiles – Guidelines for ISP Submitters*.

INDUSTRIAL COMMUNICATION NETWORKS – PROFILES –

Part 1: Fieldbus profiles

1 Scope

This part of IEC 61784 defines a set of protocol specific communication profiles based primarily on the IEC 61158 series, to be used in the design of devices involved in communications in factory manufacturing and process control.

Each profile selects specifications for the communications protocol stack at a device. It contains a minimal set of required services at the application layer and specification of options in intermediate layers defined through references. If no application layer is included, then a minimal set of required services at the Data-link layer is specified. The appropriate references to the protocol specific types are given in each communication profile family or associated profiles.

NOTE All profiles are based on standards or draft standards or International Standards published by the IEC or from standards or International Standards established by other standards bodies or open standards processes.

The structure of communication profile families is specified in Figure 1.

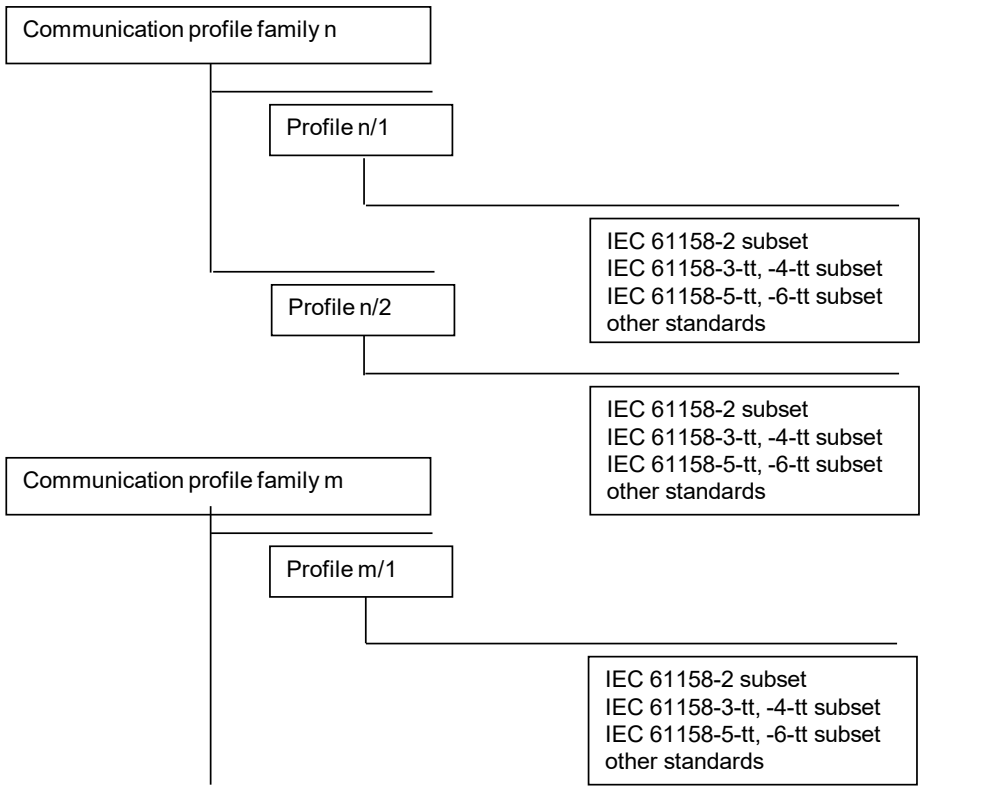


Figure 1 – Communication profile families and profiles